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June 30, 2000



Asst. Commissioner of Patents
Washington, D.C. 20231

PATENT APPLICATION TRANSMITTAL LETTER

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MICRO-SHAPE TRANSCRIPTION METHOD, MICRO-SHAPE
TRANSCRIPTION APPARATUS, AND OPTICAL-COMPONENT
MANUFACTURE METHOD

Attorney Docket No.: 33216M050

Sir:

Transmitted herewith for filing are the following:

New patent application including 21 pages of text, 9 sheets of formal
drawings, unsigned Declaration and Claim For Foreign Priority with
attached certified copy of foreign priority document.

Respectfully submitted,
SMITH, GAMBRELL & RUSSELL, LLP

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June 30, 2000



MICRO-SHAPE TRANSCRIPTION METHOD, MICRO-SHAPE TRANSCRIPTION APPARATUS, AND OPTICAL-COMPONENT MANUFACTURE METHOD

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to a method for micro-fabricating a surface of a base material and a method for manufacturing an optical component whose surface is micro-fabricated such as an optical waveguide, diffraction grating, or polarizer.

2. Related Art of the Invention

Because optical-unit related markets such as those of optical communication, optical disk, display, and optical sensor have been progressed, coexistence of high performance and low cost is requested for an optical component. Particularly, price reduction is requested for a passive optical component that itself does not operate.

Particularly, optical waveguides and diffraction gratings require a very fine and accurate pattern for their surfaces. Dry etching frequently used for a semiconductor process is generally used to form the above pattern. As an example of micro-fabrication by dry etching, a process for manufacturing a single-mode optical waveguide for optical

communication is described below by referring to the accompanying drawings.

FIG. 7(a) is a top view of a general quartz-based single-mode optical waveguide and FIG. 7(b) is a sectional view of the waveguide in FIG. 7(a), taken along the line A-A in FIG. 7(a). Because a core 71 has a refractive index higher than that of a clad 72, the light meeting a specific condition is transmitted by being confined in a core pattern. By patterning the core 71 as shown in FIG. 7(a), it is possible to constitute an optical circuit. In a wavelength band of 1.3 to 1.55 μm , the core 71 generally has a square cross section one side of which is approx. 8 μm . A core shape and a core-surface roughness greatly influence a light propagation performance.

FIGS. 8(a) to 8(c) are process charts showing a general manufacture method for a conventional quartz-based optical waveguide (refer to Kawauchi, OPTRONICS No. 8,851, 1988). In the illustrated steps, a core film 81 is formed on a quartz substrate 82 also serving as a lower clad layer in accordance with the flame deposition method (FIG. 8(a)). However, when using a substrate other than a quartz substrate, a lower clad layer is previously formed in accordance with the flame deposition method. Then, a core film is formed into a predetermined pattern through photolithography and dry etching (FIG. 8(b)). An upper clad layer 83 is then formed

in accordance with the flame deposition method (FIG. 8(c)). An optical waveguide having a small loss has been manufactured so far in accordance with the above method.

In recent years, however, not only quartz but also resin have been studied as an optical-waveguide material. At present, resin is inferior to quartz in transparency and reliability. Resin is easily molded and superior in transparency at a wavelength of approx. 650 to 850 nm, however. Therefore, it is a very prospective optical-waveguide material. Polymethyl methacrylate (PMMA) superior in transparency is known as a specific resin. Recently, it is also studied to realize low absorption in a wavelength area of 1.3 to 1.55 μm by performing deuteration or fluorination on the basis of PMMA.

To manufacture an optical waveguide by using resin, a method is generally used in which a core layer and a clad layer are formed mainly by spin coating and the core layer is patterned by dry etching. Resin has a high productivity because it has a short film deposition time and a low annealing temperature of 200 to 300°C compared to quartz.

As described above, dry etching is used to pattern a core of quartz or resin in the case of conventional optical-waveguide manufacturing.

However, dry etching is a complex process and requires a lot of equipment. Therefore, when considering cost, it

cannot be said that dry etching is suitable for manufacturing a passive optical component, setting aside a semiconductor device. Therefore, various methods are proposed for manufacturing an optical component. Particularly, pressing-molding and injection-molding methods are prospective.

Proposed examples of press-molding are exclusively directed to glass materials and include a method disclosed in the specification of Japanese Patent Laid-Open No. 8-320420. The method is an optical-waveguide manufacturing method of simultaneously forming groove portions serving as core patterns by pressing a mold 91 on which a predetermined core pattern 92 is formed against a base material 93 also serving as a lower clad at a high temperature as shown in FIG 9. The method makes it possible to efficiently form an optical waveguide by omitting the photolithography and dry-etching steps which have been used so far.

A method is also proposed in which a diffraction grating is manufactured by transcribing a pattern on a metal reflection film using pressing-molding (the specification of Japanese Patent Laid-Open No. 10-96808).

A micro-pattern transcription method using pressing-molding disclosed in the specification of Japanese Patent Laid-Open No. 8-320420 is briefly described below. First, a base material (workpiece) is heated and softened and

brought into contact with a mold. While keeping the above state, the base material is cooled and separated from the mold when the shape of the base material is fixed. In this case, as shown in FIG. 10, a convex portion 103 formed on a mold 101 is provided correspondingly to a required waveguide pattern and pressed against a resin substrate 102, and a reverse pattern is formed on the resin substrate 102.

However, when using the above transcription method, a high pattern accuracy may not be obtained. Deterioration of the pattern accuracy seems to be caused by a difference between thermal expansion coefficients. That is, when bringing the base material softened by heating into contact with the mold and cooling the base material and the mold, a thermal stress is generated due to a difference between thermal expansion coefficients of the base material and mold. As a result, the accuracy of a pattern transcribed to the base material is lowered and the mold is broken if the mold is weak in strength. This problem becomes remarkable when using resin because resin has a thermal expansion coefficient 1 to 2 digits larger than that of quartz used as the material of a mold.

According to specific study by the present inventor, the width of a groove is increased at a micron-order level and the shape of the groove is deformed by transcribing a pattern to a resin substrate by using a mold. It is estimated that this phenomenon results from the fact that the resin substrate

contracts toward the center of transcription because the substrate contracts more than the mold. This phenomenon remarkably occurs when a transcription face is a plane. Moreover, when the cross section of a micro shape is rectangular, a pattern is further deformed.

Thus, resin can be molded at a low temperature and it is advantageous in the manufacturing cost. However, it has a problem that a micro pattern cannot be accurately transcribed when transcribing a pattern by pressing-molding.

SUMMARY OF THE INVENTION

The present invention is made to solve the conventional problems and its object is to provide a method for efficiently transcribing a high-accuracy micro shape.

It is another object of the present invention to provide a method for fabricating an optical component such as an optical waveguide by using the above transcription method.

To achieve the above objects, a micro-shape transcription method of the present invention is a micro-shape transcription method comprising preparing a mold with a transcription face and including a concavo-convex pattern formed on the transcription face, pressing the transcription face against a base material softened by heating and then forcibly separating the mold from the base material, to transcribe a reverse pattern of the concavo-convex pattern to the surface

of the base material, wherein when assuming a temperature for pressing the mold against the base material as $T_1(^{\circ}\text{C})$, a temperature for separating the mold from the base material as $T_2(^{\circ}\text{C})$, thermal expansion coefficients of the mold and the base material as α_a and α_b , and the maximum distance between the transcription center of the transcription face and the concavo-convex pattern as d (mm), the following relations (1) and (2) are simultaneously satisfied.

$$T_1 \geq T_2 \quad \dots (1)$$

$$|\alpha_a - \alpha_b| \cdot (T_1 - T_2) \cdot d \leq 4 \times 10^{-2} \quad \dots (2).$$

The present invention is particularly preferable when the transcription face of a mold is a plane or a stepped plane.

Moreover, the present invention is particularly preferable when the sectional form of a concavo-convex pattern is rectangular.

Furthermore, the present invention is particularly preferable when $|\alpha_a - \alpha_b|$ is equal to or higher than $50 \times 10^{-7}/^{\circ}\text{C}$.

Furthermore, the present invention is particularly preferable when the line width of a concavo-convex pattern is equal to or less than $100 \mu\text{m}$.

Furthermore, the present invention is particularly preferable when the depth of a concavo-convex pattern is equal to or more than $1 \mu\text{m}$.

Furthermore, in the above described method of the present invention, a base material is preferably an optically

transparent thermoplastic resin or glass. It is preferable to use any one of polyolefin, polymethyl methacrylate, polycarbonate, norbornane, and acrylic resins as the thermoplastic resin.

A micro-shape transcription apparatus of the present invention comprises a first mold provided with a transcription face having a micro-shape, a second mold facing the first mold, a mechanism for driving either of the first and second molds, a heating source for controlling the temperatures of the first and second molds, and a vacuum chuck for attracting and fixing a base material to the second mold.

An optical-component manufacturing method of the present invention forms a pattern for controlling light in accordance with the above-described micro-shape transcription method. An optical component of the present invention includes an optical waveguide, diffraction grating, polarizer, or lens. When the optical component is an optical waveguide, a pattern corresponding to a core is formed in accordance with a micro-shape transcription method of the present invention.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a sectional view showing a configuration of a pressing machine used for an embodiment of a micro-shape transcription method of the present invention;

FIGS. 2(a) and 2(b) are illustrations showing a pattern formed on a transcription face of a mold used for an embodiment of a micro-shape transcription method of the present invention;

FIG. 3 is a sectional perspective view showing an example of an optical waveguide formed by the machine shown in FIG. 1;

FIG. 4 is an SEM photograph of a cross section of a resin substrate obtaining a preferable transcription quality from an embodiment of the present invention;

FIG. 5 is an SEM photograph of a cross section of a resin substrate obtaining a bad transcription quality from an embodiment of the present invention;

FIG. 6 is a photograph showing a result of measuring the surface shape of a resin substrate obtaining a preferable transcription quality by an embodiment of the present invention;

FIG. 7(a) is a top view of a general quartz-based single-mode optical waveguide and FIG. 7(b) is a sectional view of the waveguide in FIG. 7(a);

FIGS. 8(a) to 8(c) are process charts showing a method for manufacturing a conventional general optical waveguide;

FIG. 9 is a sectional view showing a conventional method for manufacturing an optical waveguide through pressing; and

FIG. 10 is a conventional pattern used for a method for manufacturing an optical waveguide through pressing.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

Embodiments of the present invention are described below by referring to the accompanying drawings.

FIG. 1 shows a pressing machine used for a micro-shape transcription method of the present invention. The machine is provided with a pair of upper and lower heater blocks 11 and 12. The upper heater block 11 is vertically movable and the lower heater block 12 is fixed. A cope 13 is fixed to the upper heater block 11 with the transcription face turning downward. The cope 13 is made of quartz having a size of 20×20 mm and has a micro shape formed through dry etching on the flat transcription face. FIGS. 2(a) and 2(b) show a pattern formed on the transcription face of a cope 21. FIG. 2(a) is a top view of the pattern and FIG. 2(b) is a sectional view of the pattern in FIG. 2(a), taken along the line A-A in FIG. 2(a). In this case, the pattern is convex. The convex pattern 22 has a depth of approx. 5 μm and a width of approx. 8 μm .

In this case, a polyolefin-based thermoplastic resin is used as a base material 14 to be formed. This resin is optically transparent and has a glass-transition temperature of 140°C and a load deflection temperature of 123°C. The base material has a size of 8×8 mm and is set on a planar drag 15 fixed on the lower heater block 12. The base material 14 is fixed to the drag 15 by a vacuum chuck.

A micro-shape transcription method is described below by referring to FIG. 1.

The quartz mold 13 serving as a cope and the resin substrate 14 serving as a workpiece are overlapped at the molding machine so that the transcription face of the quartz mold 13 contacts with the resin substrate 14. In this case, the center of the quartz mold 13 is almost adjusted to the center of the resin substrate 14. Under the above state, the upper and lower heater blocks 11 and 12 are electrified, the resin substrate 14 is heated up to 180°C to be softened, and the upper heater block 11 to which the quartz mold 13 is fixed is moved downward and pressed. While a convex pattern of the quartz mold 13 bites into the resin substrate 14, heater temperature is lowered to 150°C by controlling electrification of upper and lower heaters and the upper heater block 11 is raised to forcibly separate the cope 13 from the resin substrate 14. In this case, the resin substrate 14 is fixed to the drag 15 by a vacuum chuck and smoothly separated from the cope 13 without being distorted or deformed. Thereafter, the resin substrate 14 is cooled up to approx. room temperature and taken out of the molding machine.

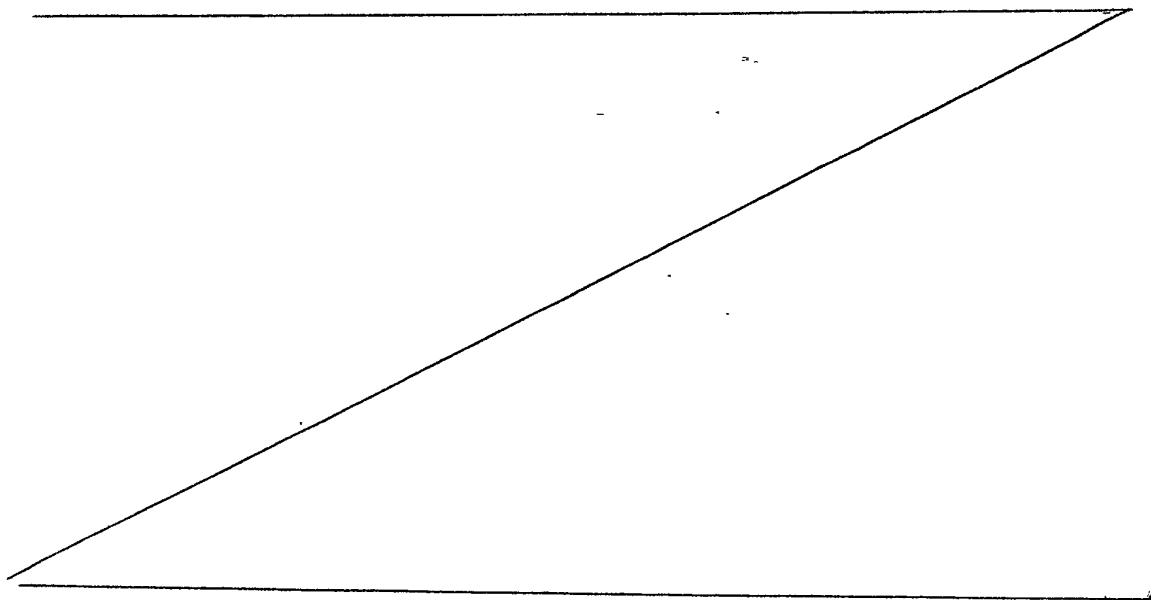
As a result of observing the surface and cross section of the taken-out resin substrate by an optical microscope and an electron microscope, the groove of a micro-pattern to which the convex pattern of the quartz mold is accurately transcribed

is confirmed over the entire surface of a resin substrate having a diameter of approx. 20 mm.

Then, epoxy resin having a refractive index approx. 0.3% higher than that of the resin substrate is embedded in the groove of the resin substrate and a flat resin substrate made of the same material as the above resin substrate is bonded onto the above resin substrate. Thus, the optical waveguide shown in FIG. 3 is fabricated.

The optical waveguide is provided with epoxy resin as a core 32 and polyolefin resin substrates as clads 31, 33. The optical waveguide has a sufficient serviceability.

Moreover, molding is studied by using a molding temperature which is a temperature for pressing a mold against a resin substrate and a mold releasing temperature which is a temperature for releasing the mold from the resin substrate as parameters and the resin substrate is observed after molding. Table 1 shows an example of observation results.



[Table 1]

Molding temperature	Mold releasing temperature	Transcription-quality evaluation
160	80	×
160	90	×
160	100	○
160	120	○
160	140	○
180	80	×
180	100	×
180	120	○
180	150	○

In the case of Table 1, the quality of a transcription shape is observed at a position 1 cm separate from the transcription center of a transcription face. In this case, an object transcribed at a submicron accuracy is judged as O and an object not transcribed at a submicron accuracy is judged as ×.

FIGS. 4 and 5 show electron micrographs of the cross sections of a groove transcribed onto a resin substrate.

In the case of FIGS. 4 and 5, cross sections are obtained by coating the formed resin substrate with a metallic film, embedding it in epoxy resin, and polishing it, and lower

portions show the formed substrate. A while boundary line shows the metallic film. FIG. 4 is obtained at a molding temperature of 180°C and a mold releasing temperature of 150°C at which the transcription quality is judged to be good, and FIG. 5 is obtained at a molding temperature of 180°C and a mold releasing temperature of 80°C at which the transcription quality is judged to be bad.

FIG. 6 shows the result of measurement of the surface roughness of a groove pattern, which was obtained at a molding temperature of 180°C and a mold releasing temperature of 150°C at which the transcription quality is judged to be good, by a non-contact roughness meter.

The photograph is overlapped with a photograph when viewing a groove from the surface, the sectional form is shown by leader lines L1 to L5, and the groove has a width of 7.8 μm and a depth of 4.68 μm . The irregularity of the surface of the molded resin substrate is originally present on a quartz mold.

Thereby, it is confirmed that the groove is vertical and transcribed at a roughness of a submicron level or lower. That is, it is found that transcription is smoothly performed even if measuring methods are changed.

The following Equation 1 is calculated on the above result.

[Equation 1]

$$M = |\alpha_a - \alpha_b| \cdot (T_1 - T_2) \cdot d \quad \dots \text{Equation 1}$$

In the above Equation, α_a denotes a thermal expansion coefficient of quartz serving as a mold and α_b denotes a thermal expansion coefficient of polyolefin-based resin serving as a workpiece, in which α_a is equal to $5 \times 10^{-7}/^{\circ}\text{C}$ and α_b is equal to $600 \times 10^{-7}/^{\circ}\text{C}$. Moreover, T_1 denotes a molding temperature and T_2 denotes a mold releasing temperature. Symbol d (mm) denotes the distance between the position at which transcription quality is evaluated and the transcription center.

As a result of calculating the Equation 1 on each molding condition in Table 1, it is found that a preferable transcription quality is obtained in the case of $M \leq 4 \times 10^{-2}$. As for the above relation, it is found that the same result is obtained even if using one of polymethyl-methacrylate-, polycarbonate-, acrylic-, and norbornane-based thermoplastic resins or glass for a substrate to be molded, using one of various metals including nickel, various ceramics including zirconium, WC-based cemented carbide, diamond film, and DLC for a mold base material, combining various mold materials with a material to be molded, and changing molding conditions. That is, it is clarified that a micro shape can be transcribed as long as a molding condition meets the condition of Expression 1.

In this embodiment, manufacturing of an optical waveguide is described. However, a method of the present invention is

not restricted to the above case but it is suitable for manufacturing all components requiring a micro pattern including an optical component, mechanical component, and micromechanics-related component. It is particularly suitable for manufacturing a high-accuracy optical component including an optical waveguide, diffraction grating, polarizer and lens.

Moreover, for this embodiment, a mold provided with a convex pattern is used. However, the same advantage can be obtained by using a concave pattern or a concavo-convex pattern. A pattern sectional form is not restricted. For example, the mold is effective for a trapezoidal shape, triangular shape, or wave shape. The mold is particularly effective for a micro shape having a rectangular cross section on a flat transcription face that is easily influenced by thermal expansion and on which a pattern easily collapses.

Moreover, for this embodiment, the flat pattern shape shown in FIG. 2 is described. However, a pattern shape is not restricted to the flat pattern shape.

Furthermore, as a result of studying various materials, it is found that a method of the present invention is particularly effective when a difference between thermal expansion coefficients of a mold and a base material is $50 \times 10^{-7}/^{\circ}\text{C}$ or more, a pattern has a width of $100 \mu\text{m}$ or less, and a concavo-convex pattern has a depth of $1 \mu\text{m}$ or more. That

is, under the above conditions, separation cannot be made by a conventional method but separation can be realized by the present invention.

Moreover, though a material of a mold or a material to be molded is not restricted, the mold is particularly effective for a thermoplastic resin having a comparatively large thermal expansion coefficient. By applying protective coating to a mold and performing molding in an inert-gas atmosphere, it is possible to transcribe a micro pattern to glass.

As described above, the present invention makes it possible to efficiently transcribe a high-accuracy micro pattern.

Moreover, the present invention makes it possible to efficiently manufacture an optical component such as an optical waveguide.

Particularly, the present invention makes it possible to accurately transcribe a micro pattern to a wide area of resin having a large thermal expansion coefficient that is a problem as a material of an optical component.

Thus, according to the present invention, it is possible to efficiently manufacture various optical components including an optical waveguide and a diffraction grating.

What is claimed is

1. A micro-shape transcription method comprising preparing a mold having a transcription face on which a concavo-convex pattern is formed, pressing the transcription face against a base material softened by heating, then forcibly separating the mold from the base material to transcribe a reverse pattern of the concavo-convex pattern to the surface of the base material, wherein when assuming a temperature for pressing the mold against the base material as $T_1(^{\circ}\text{C})$, a temperature for separating the mold from the base material as $T_2(^{\circ}\text{C})$, thermal expansion coefficients of the mold and the base material as α_a and α_b , and the maximum distance between the transcription center of the transcription face and the concavo-convex pattern as d (mm), the following relations (1) and (2):

$$T_1 \geq T_2 \quad \dots (1)$$

$$|\alpha_a - \alpha_b| \cdot (T_1 - T_2) \cdot d \leq 4 \times 10^{-2} \quad \dots (2)$$

are simultaneously satisfied.

2. The micro-shape transcription method according to claim 1, wherein the transcription face of the mold is a plane or stepped plane.

3. The micro-shape transcription method according to claim 1 or 2, wherein the sectional form of the concavo-convex pattern is rectangular.

4. The micro-shape transcription method according to claim 1 or 2, wherein the value $|\alpha_a - \alpha_b|$ is $50 \times 10^{-7}/^{\circ}\text{C}$ or higher.

5. The micro-shape transcription method according to claim 1 or 2, wherein the concavo-convex pattern has a line width of 100 μm or less.

6. The micro-shape transcription method according to claim 1 or 2, wherein the concavo-convex pattern has a depth of 1 μm or more.

7. The micro-shape transcription method according to claim 1 or 2, wherein the base material uses an optically-transparent thermoplastic resin or glass.

8. The micro-shape transcription method according to claim 7, wherein the thermoplastic resin is selected from the group consisting of polyolefin-, polymethyl-methacrylate-, polycarbonate-, norbornane-, and acrylic-based resins.

9. A micro-shape transcription apparatus comprising a first mold provided with a transcription face having a micro-shape, a second mold facing the first mold, a mechanism for driving either of the first and second molds, a heating source for controlling temperatures of the first and second molds, and

a vacuum chuck for attracting and fixing a base material to the second mold; wherein

a micro-shape is transcribed in accordance with the micro-shape transcription method of claim 1 or 2.

10. An optical-component manufacturing method wherein a pattern for controlling light of an optical component is formed in accordance with the micro-shape transcription method of claim 1 or 2.

11. An optical waveguide manufacturing method wherein a pattern corresponding to a core of an optical component is formed in accordance with the micro-shape transcription method of claim 1 or 2.

ABSTRACT

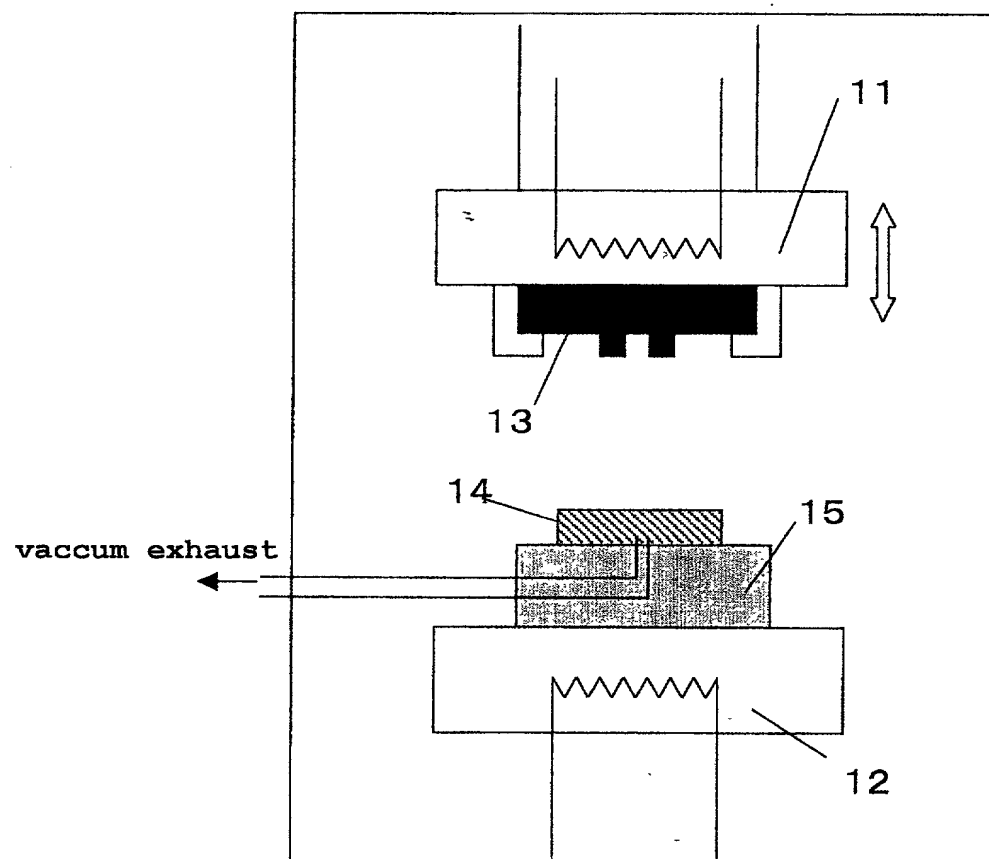
A micro-shape transcription method has preparing a mold having a transcription face on which a concavo-convex pattern is formed, pressing the transcription face against a base material softened by heating, then forcibly separating the mold from the base material to transcribe a reverse pattern of the concavo-convex pattern to the surface of the base material, wherein when assuming a temperature for pressing the mold against the base material as $T_1(^{\circ}\text{C})$, a temperature for separating the mold from the base material as $T_2(^{\circ}\text{C})$, thermal expansion coefficients of the mold and the base material as α_a and α_b , and the maximum distance between the transcription center of the transcription face and the concavo-convex pattern as d (mm), the following relations (1) and (2):

$$T_1 \geq T_2 \quad \dots (1)$$

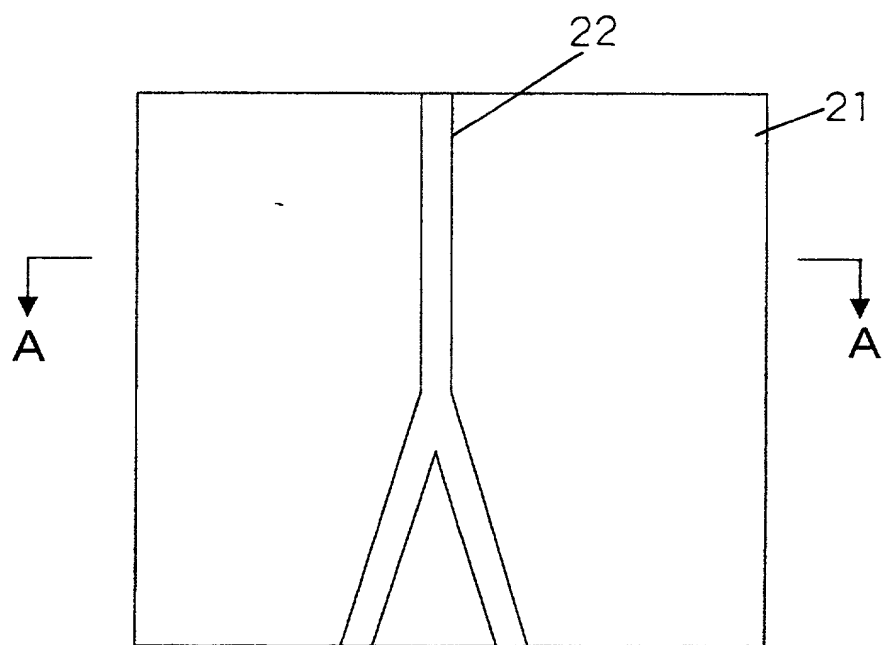
$$|\alpha_a - \alpha_b| \cdot (T_1 - T_2) \cdot d \leq 4 \times 10^{-2} \quad \dots (2)$$

are simultaneously satisfied.

F i g . 1



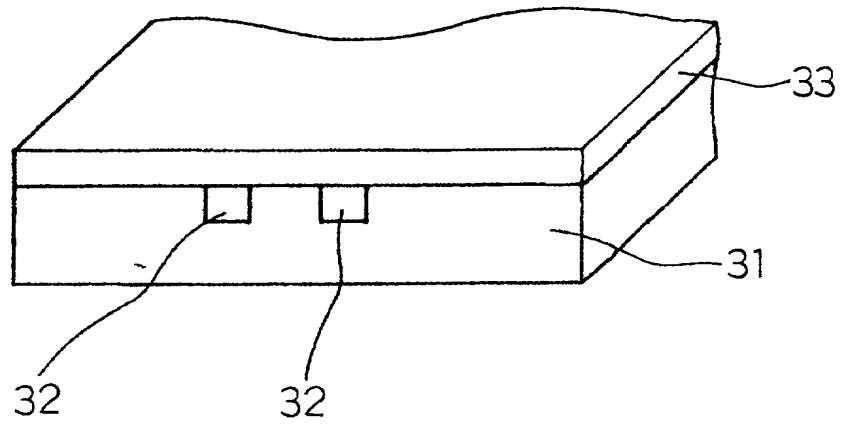
F i g . 2 (a)



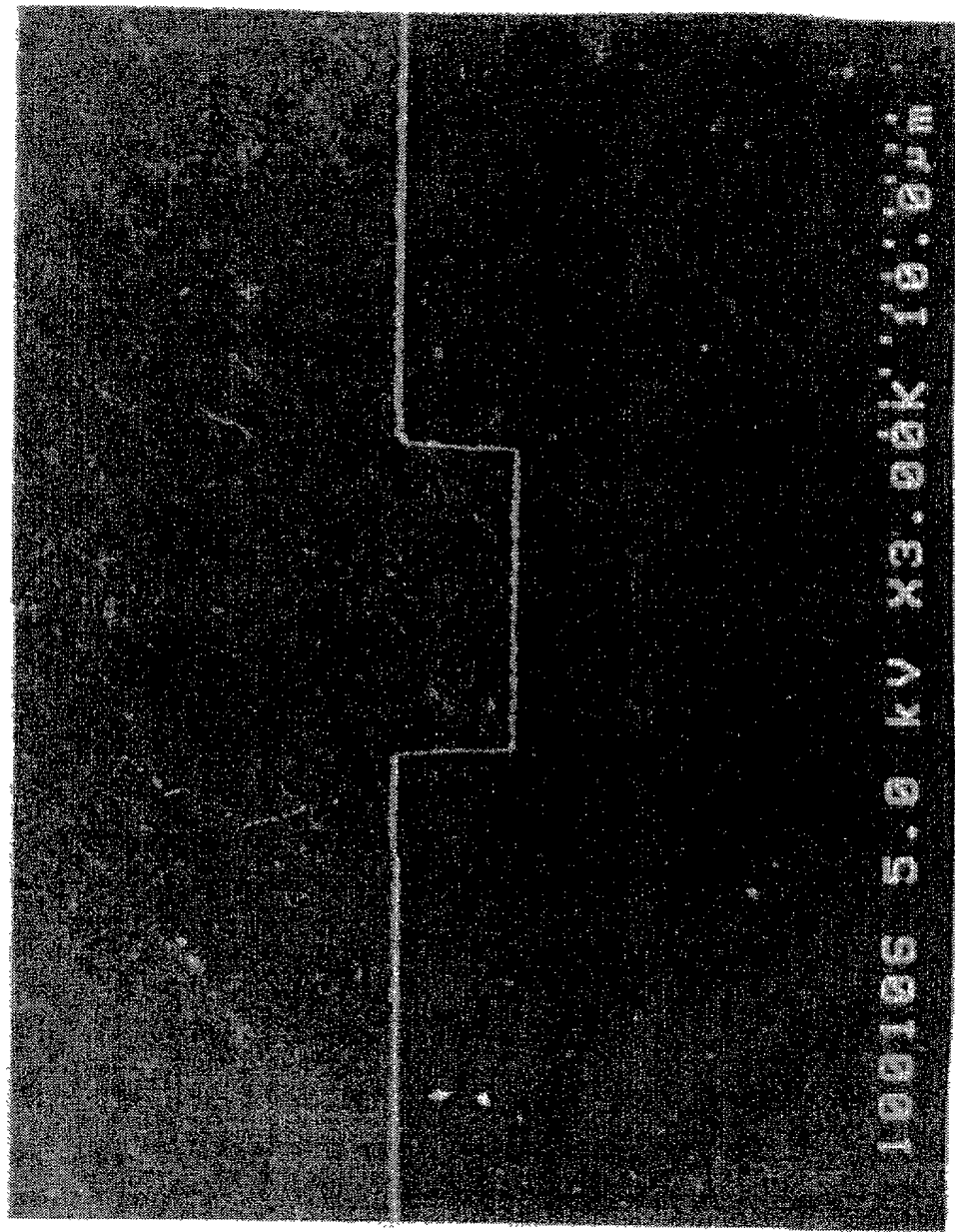
F i g . 2 (b)



F i g . 3



4511



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F i g . 5

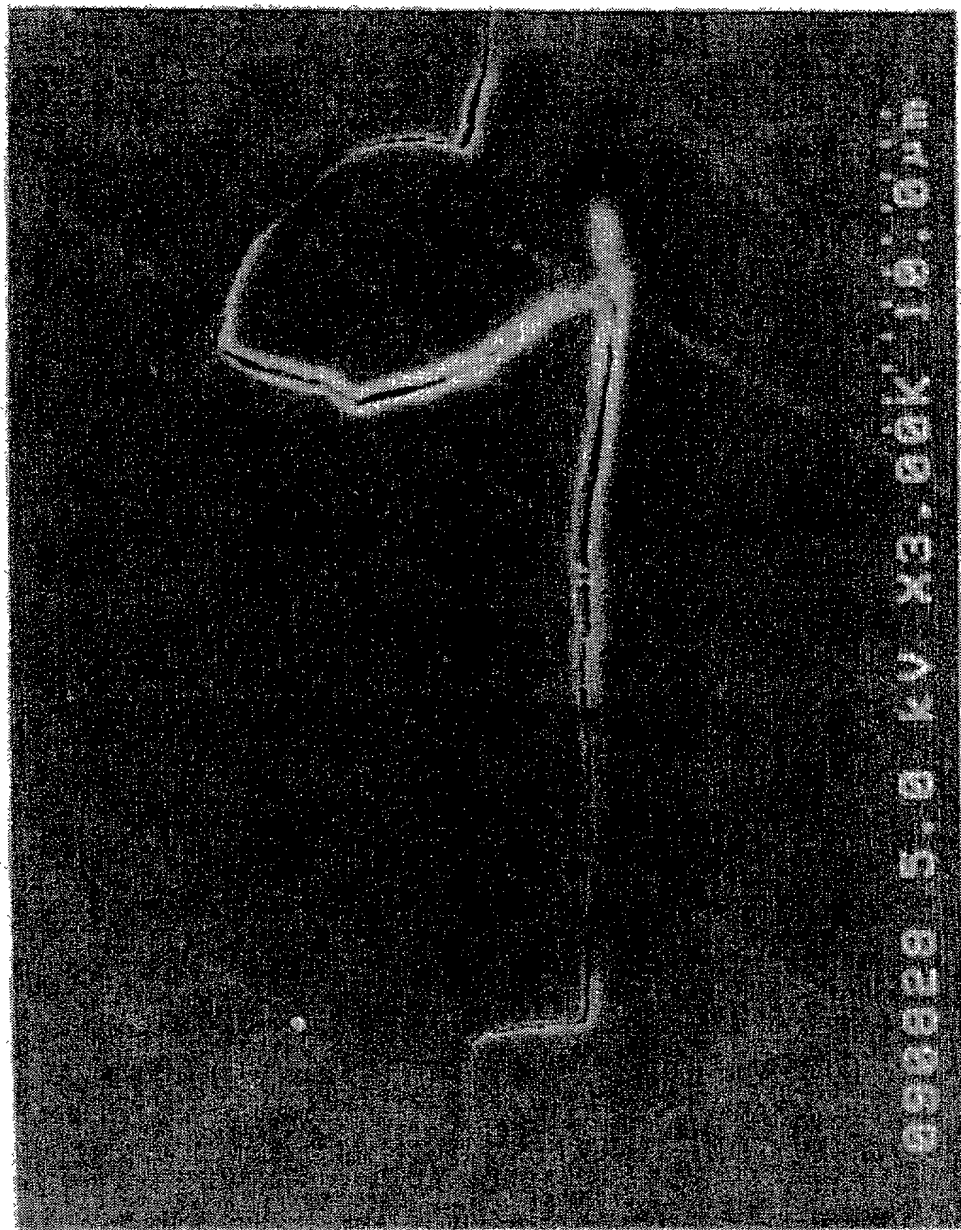
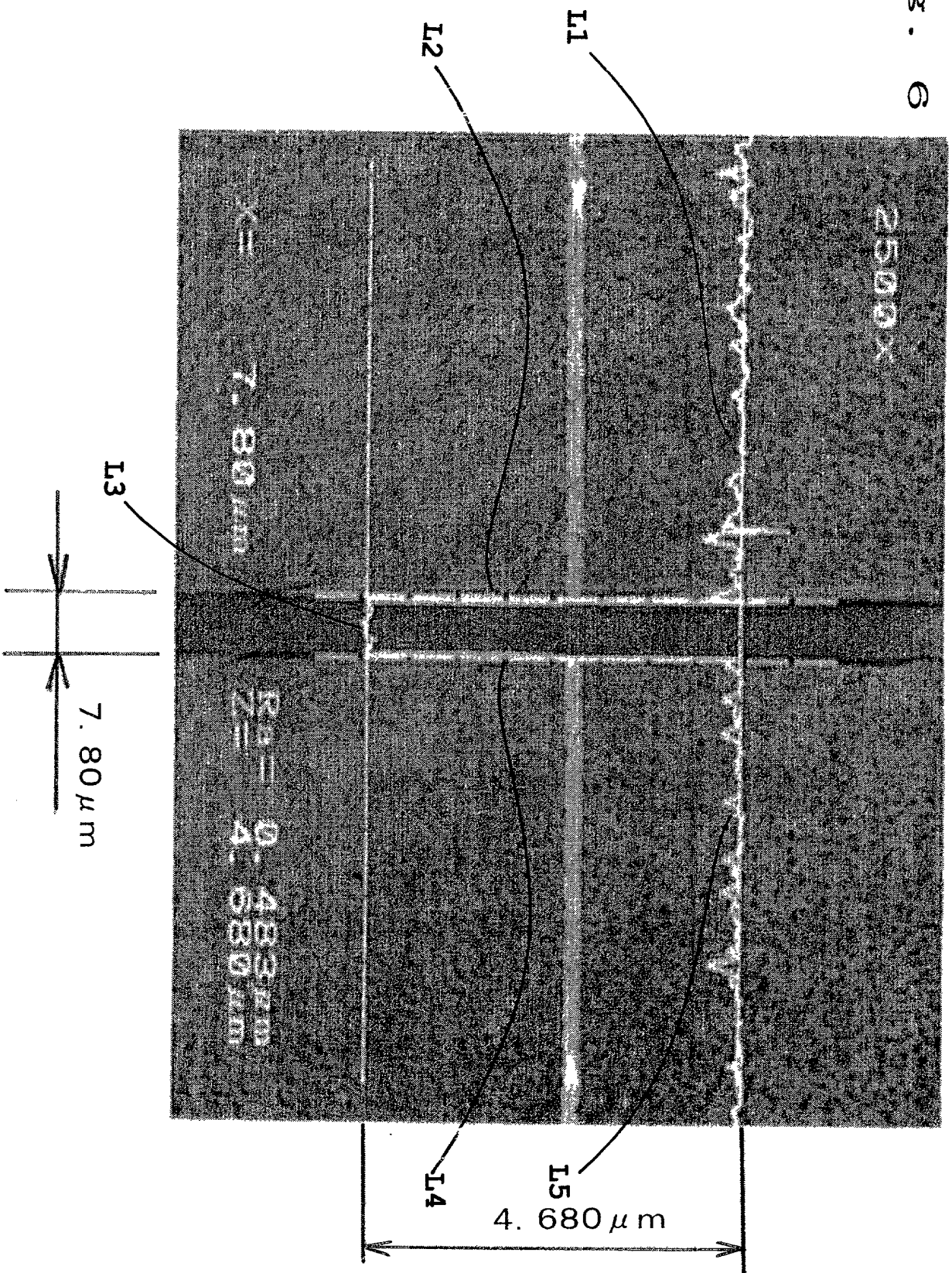
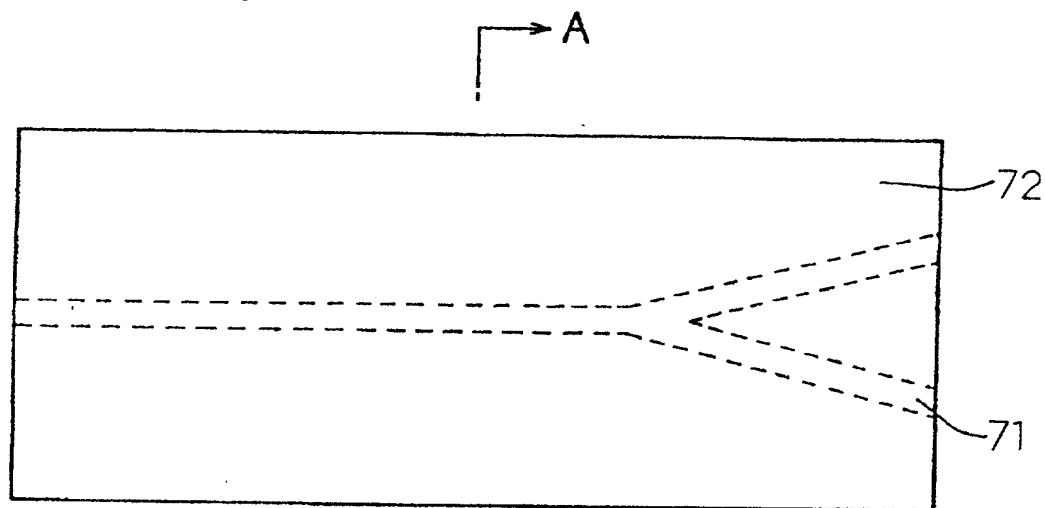


Fig. 6

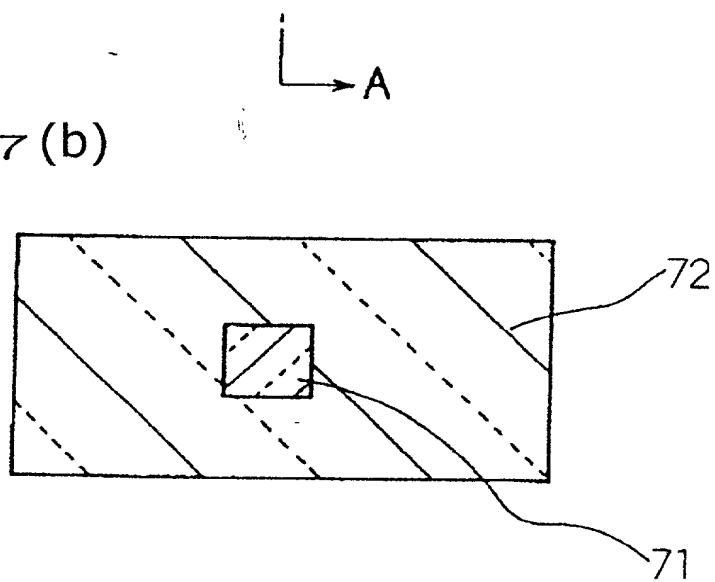


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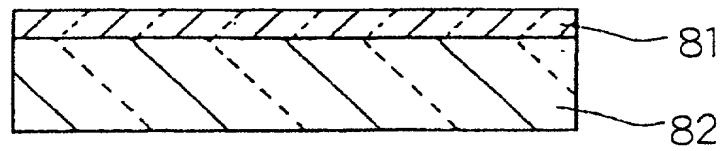
F i g . 7 (a)



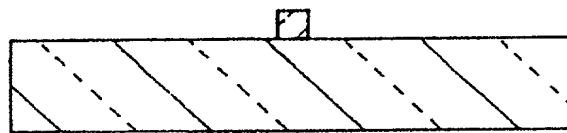
F i g . 7 (b)



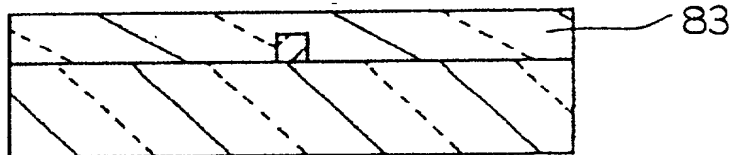
F i g . 8 (a) PRIOR ART



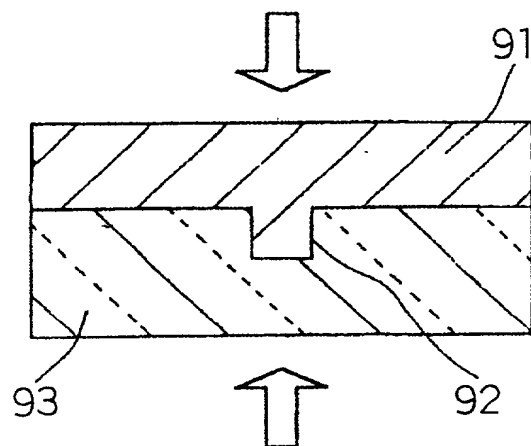
F i g . 8 (b) PRIOR ART



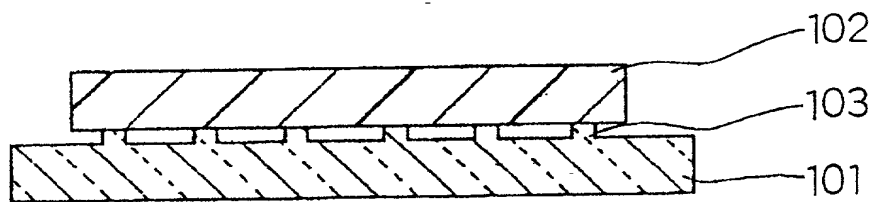
F i g . 8 (c) PRIOR ART



F i g . 9 PRIOR ART



F i g . 10 PRIOR ART



Declaration and Power of Attorney United States Patent Application

UNITED STATES (Form BDWY-1)
Patents and Design Patents
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Convention & Non-convention
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This form cannot be amended, altered
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As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled **MICRO-SHAPE TRANSCRIPTION METHOD, MICRO-SHAPE TRANSCRIPTION APPARATUS, AND OPTICAL-COMPONENT MANUFACTURE METHOD**

- (check one) ☐ is attached hereto.
☐ was filed as U.S. Application No. _____ on _____ and (if applicable) was amended on _____.
☐ was filed as PCT International Application No. _____ on _____ and (if applicable) was amended under PCT Article 19 on _____.
(I authorize any attorney appointed below to insert information in the preceding blanks.)

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.
I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) or §365(b) of any foreign and PCT application(s) for patent or inventor's certificate, or §365(a) of any PCT international application which designated at least one country other than the United States of America listed in this Declaration. I have also identified below any foreign application for patent or inventor's certificate or PCT international application having a filing date before that of the application(s) on which priority is claimed:

Foreign/PCT Application No.	Country	Filing Date	Priority Claimed? (yes/no)
Hei 11-199,616	JAPAN	July 13, 1999	YES

I hereby claim the benefit under Title 35, United States Code, §120 or §365(c) of any United States application and PCT international application designating the United States of America listed in this Declaration and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application or PCT international application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

U.S. Application No.	Filing Date	Status (patented/pending/abandoned?)

I hereby claim priority benefits under Title 35 United States Code §119(e) of any U.S. provisional application(s) listed below:

U.S. Provisional Application No.	Filing Date

I hereby appoint the following attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith: Joseph A. DeGrandi (17446), Robert G. Weilacher (20531), Richard G. Young (20628), Michael A. Makuch (32263), Dennis C. Rodgers (32936), Thomas L. Evans (35805), Frank C. Cimino, Jr. (39945), Carolyn Favorito (39183), George A. Metzenthin (P41995), and Steven W. Collier (P42429).

Send all correspondence to Beveridge, DeGrandi, Weilacher & Young, L.L.P., Suite 800, 1850 M Street, N.W., Washington, D.C. 20036. Facsimiles may be sent to (202) 659-1462. Direct all telephone calls to (202) 659-2811.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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☐ Additional inventors and/or prior applications are listed in attached Supplemental Sheet(s).

Supplemental Sheet to U.S. Declaration and Power of Attorney

(BDWY-1 supp.)

Additional Inventor(s):

I hereby declare that all statements made in the attached Declaration and Power of Attorney of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Full name of inventor:

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Signature: _____ Date: _____

Full name of inventor:

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Signature: _____ Date: _____

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Signature: _____ Date: _____

Additional Foreign/PCT Applications:

Foreign/PCT Application No.	Country	Filing Date	Priority Claimed? (yes/no)

Additional U.S. Applications:

U.S. Application No.	Filing Date	Status (patented/pending/abandoned?)

Additional Provisional U.S. Applications:

U.S. Provisional Application No.	Filing Date